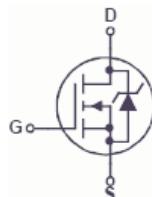
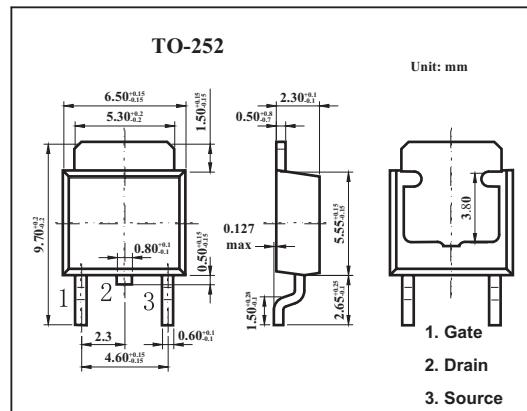


N-Channel PowerTrench MOSFET

KDD2572

■ Features

- $r_{DS(ON)} = 45\text{m}\Omega$ (Typ.), $V_{GS} = 10\text{V}$, $I_D = 9\text{A}$
- $Q_g(\text{tot}) = 26\text{nC}$ (Typ.), $V_{GS} = 10\text{V}$
- Low Miller Charge
- Low QRR Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101



■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-------------------|------------|---------------------------|
| Drain to Source Voltage | V_{DSS} | 150 | V |
| Gate to Source Voltage | V_{GS} | ± 20 | V |
| Drain Current Continuous ($T_c = 25^\circ\text{C}$, $V_{GS} = 10\text{V}$) | I_D | 29 | A |
| Drain Current Continuous ($T_c = 100^\circ\text{C}$, $V_{GS} = 10\text{V}$) | | 20 | A |
| Drain Current Continuous ($T_c = 100^\circ\text{C}$, $V_{GS} = 10\text{V}$, $R_{JA} = 52^\circ\text{C}/\text{W}$) | | 4 | A |
| Single Pulse Avalanche Energy * | E_{AS} | 36 | mJ |
| Power dissipation | P_D | 135 | W |
| Derate above 25°C | P_D | 0.9 | W/ $^\circ\text{C}$ |
| Operating and Storage Temperature | T_J , T_{STG} | -55 to 175 | $^\circ\text{C}$ |
| Thermal Resistance Junction to Case | R_{JC} | 1.11 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance Junction to Ambient to 252 | R_{JA} | 100 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance Junction to Ambient to 252, 1in ² copper pad area | R_{JA} | 52 | $^\circ\text{C}/\text{W}$ |

* Starting $T_J = 25^\circ\text{C}$, $L = 0.2 \text{ mH}$, $I_{AS} = 19\text{A}$.

KDD2572

■ Electrical Characteristics Ta = 25°C

| Parameter | Symbol | Testconditons | Min | Typ | Max | Unit |
|-----------------------------------|---------------------|---|-----|-------|-------|------|
| Drain to Source Breakdown Voltage | BVDSS | ID = 250 μ A, VGS = 0V | 150 | | | V |
| Zero Gate Voltage Drain Current | IDSS | VDS = 120V, VGS = 0V | | | 1 | μ A |
| | | VDS = 120V, VGS = 0V, Tc = 150°C | | | 250 | |
| Gate to Source Leakage Current | IGSS | VGS = ±20V | | | ±100 | nA |
| Gate Threshold Voltage | VGS(th) | VDS = VGS, ID = 250 μ A | 2 | 4 | | V |
| Drain to Source On-Resistance | RDS(ON) | ID = 9A, VGS = 10V | | 0.045 | 0.054 | Ω |
| | | ID = 4A, VGS = 6V, | | 0.05 | 0.075 | |
| | | ID = 9A, VGS = 10V, Tc = 175°C | | 0.126 | 0.146 | |
| Input Capacitance | Ciss | VDS = 25V, VGS = 0V, f = 1MHz | | 1770 | | pF |
| Output Capacitance | Coss | | | 183 | | pF |
| Reverse Transfer Capacitance | CRSS | | | 40 | | pF |
| Total Gate Charge at 10V | Qg(TOT) | VGS = 0V to 10V, VDD = 75V, ID = 9A, Ig = 1.0mA | | 26 | 34 | nC |
| Threshold Gate Charge | Qg(TH) | VGS = 0V to 2V, VDD = 75V, ID = 9A, Ig = 1.0mA | | 3.3 | 4.3 | nC |
| Gate to Source Gate Charge | Qgs | VDD = 75V, ID = 9A, Ig = 1.0mA | | 8 | | nC |
| Gate Charge Threshold to Plateau | Qgs2 | | | 5 | | nC |
| Gate to Drain "Miller" Charge | Qgd | | | 6 | | nC |
| Turn-On Time | t _{ON} | VDD = 75V, ID = 33A, VGS = 10V, RGS = 11 Ω | | | 36 | ns |
| Turn-On Delay Time | t _{d(ON)} | | | | 11 | ns |
| Rise Time | t _r | | | | 14 | ns |
| Turn-Off Delay Time | t _{d(OFF)} | | | | 31 | ns |
| Fall Time | t _f | | | | 14 | ns |
| Turn-Off Time | t _{OFF} | | | | 66 | ns |
| Source to Drain Diode Voltage | VSD | ISD = 9A | | | 1.25 | V |
| | | ISD = 4A | | | 1.0 | V |
| Reverse Recovery Time | t _{rr} | ISD = 9A, dISD/dt = 100A/ μ s | | | 74 | ns |
| Reverse Recovery Charge | QRR | ISD = 9A, dISD/dt = 100A/ μ s | | | 169 | nC |